



**N-CHANNEL ENHANCEMENT MOSFET**

**VDS=20V, ID=800mA**



**DESCRIPTION**

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

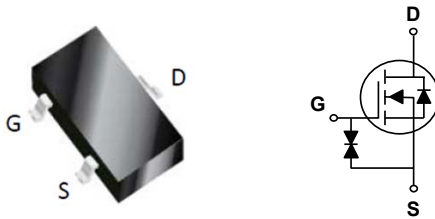
**FEATURES**

- 20V, 800mA,  $R_{DS(ON)} \leq 300m\Omega @ V_{GS}=4.5V$
- Improved dv/dt Capability
- Fast Switching
- Green Device Available
- Suit for 1.5V Gate Drive Applications
- Marking : k

**APPLICATIONS**

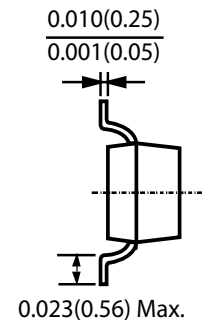
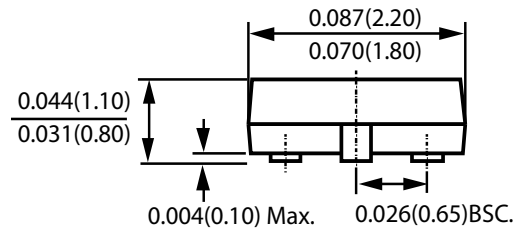
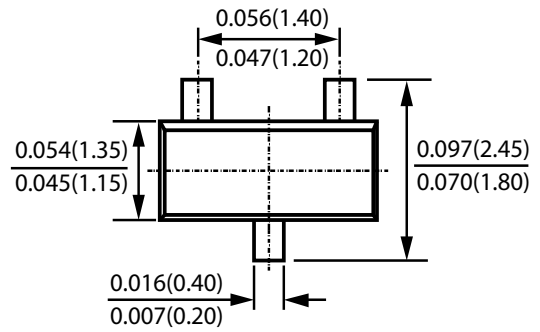
- Notebook
- Load Switch
- Battery Protection
- Hand-Held Instruments

**SOT-323 PIN CONFIGURATION**



**SOT-323**

nit:inch(mm)



**Maximum Ratings @ T<sub>C</sub>=25°C unless otherwise noted**

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V <sub>DSS</sub>	20	V
Gate-Source Voltage	V <sub>GSS</sub>	±8	V
Drain Current - Continuous	I <sub>D</sub>	T <sub>C</sub> =25°C	800 mA
		T <sub>C</sub> =100°C	510 mA
Drain Current - Pulsed (NOTE 1)	I <sub>DM</sub>	3.2	A
Power Dissipation (T <sub>C</sub> =25°C)	P <sub>D</sub>	275	mW
Thermal Resistance Junction to Ambient	R <sub>θJA</sub>	450	°C/W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-50 to +150	°C

# DEVICE CHARACTERISTICS

## YSE2320ZW

### Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise noted)

#### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	20	---	---	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±6V, V <sub>DS</sub> =0V	---	---	±20	uA

#### On Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance (NOTE 3)	V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.5A	---	200	300	mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =0.4A	---	235	400	
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =0.2A	---	295	550	
		V <sub>GS</sub> =1.5V, I <sub>D</sub> =0.1A	---	365	800	
		V <sub>GS</sub> =1.2V, I <sub>D</sub> =0.1A	---	600	1500	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.3	0.6	1.0	V

#### Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.5A (NOTE 2、3)	---	1	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	0.26	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	0.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =10V, V <sub>GS</sub> =4.5V, R <sub>G</sub> =10Ω, I <sub>D</sub> =0.5A (NOTE 2、3)	---	5	---	ns
T <sub>r</sub>	Rise Time		---	3.5	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	14	---	
T <sub>f</sub>	Fall Time		---	6	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1MHz	---	38.2	---	pF
C <sub>oss</sub>	Output Capacitance		---	14.4	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	6	---	

#### Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	0.8	A
I <sub>SM</sub>	Pulsed Source Current		---	---	1.6	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =0.2A, T <sub>J</sub> =25°C	---	---	1	V

#### NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

# DEVICE CHARACTERISTICS

## YSE2320ZW

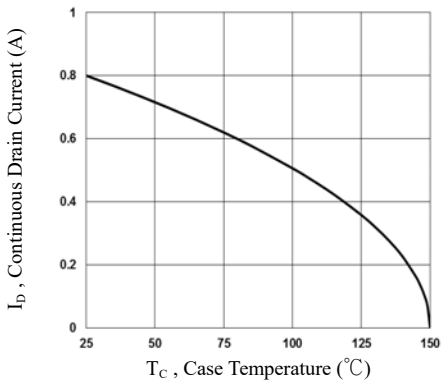


Fig.1 Continuous Drain Current vs.  $T_C$

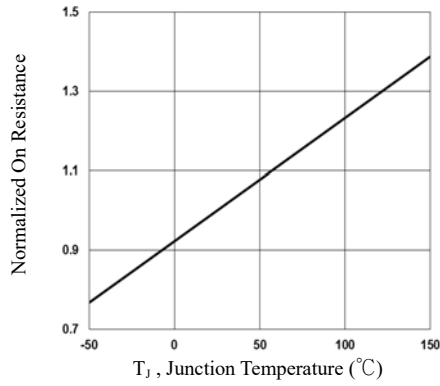


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_J$

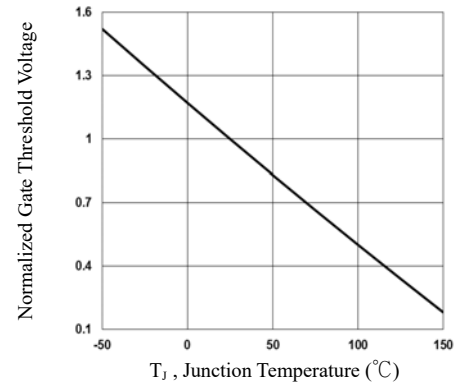


Fig.3 Normalized  $V_{th}$  vs.  $T_J$

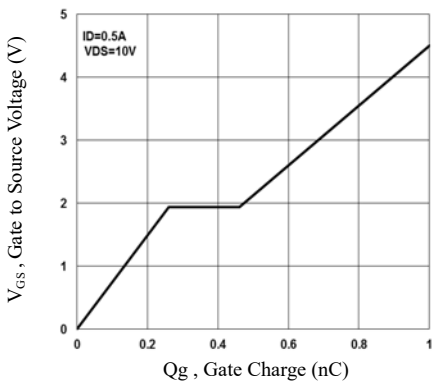


Fig.4 Gate Charge Waveform

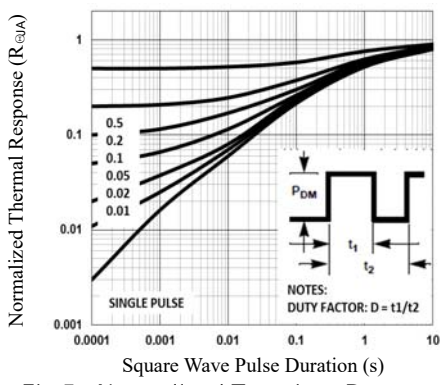


Fig.5 Normalized Transient Response

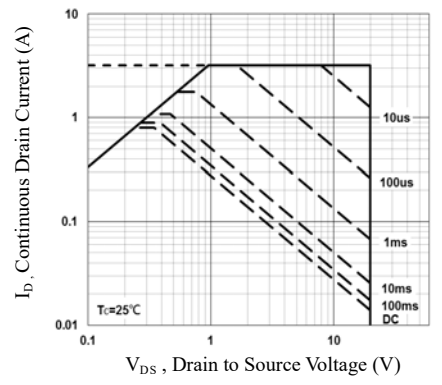


Fig.6 Maximum Safe Operation Area

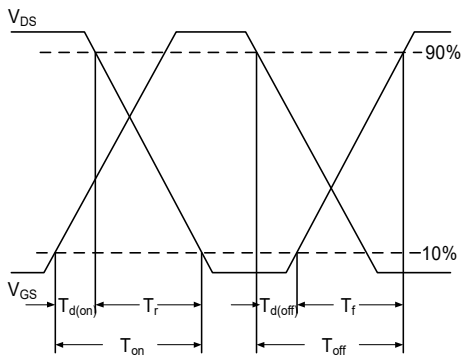


Fig.7 Switching Time Waveform